

GL Silicon N-Channel Power MOSFET

General Description:

The GL6002 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is SOT-23-3L, which accords with the RoHS standard.

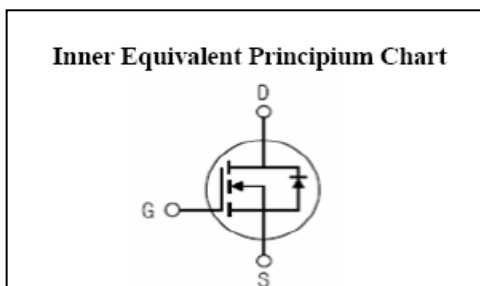
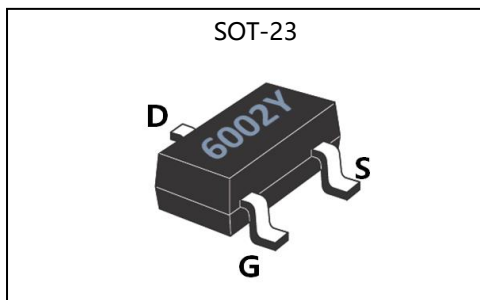
Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- PWM applications
- Load switch
- Power management

V_{DSS}	60	V
I_D	2	A
P_D	1.7	W
$R_{DS(ON)max}$	180	mΩ



Absolute (Tc=25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current	2.0	A
	Continuous Drain Current $T_C = 70^\circ\text{C}$	1.4	A
I_{DM}^{a1}	Pulsed Drain Current	8	A
V_{GS}	Gate-to-Source Voltage	± 20	V
dv/dt^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	1.7	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	300	$^\circ\text{C}$

**GL Silicon N-Channel Power MOSFET****Electrical Characteristics** (Tc=25°C unless otherwise specified) :**OFF Characteristics**

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu A$, Reference 25°C	--	0.1	--	V/°C
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=60, V_{GS}=0V, T_a=25^\circ C$	--	--	1	μA
		$V_{DS}=48V, V_{GS}=0V, T_a=125^\circ C$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V$	--	--	1	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V$	--	--	-1	μA

ON Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=3.0A$	--	135	180	mΩ
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5V, I_D=3.0A$	--	160	220	mΩ
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	--	2.5	V
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=15V, I_D=1.0A$	2	--	--	S
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=30V$ $f=1.0MHz$	--	120	--	pF
C_{oss}	Output Capacitance		--	16	--	
C_{rss}	Reverse Transfer Capacitance		--	10	--	

Resistive Switching Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=1A, V_{DD}=30V$ $V_{GS}=10V, R_G=1.0\Omega$	--	3	--	ns
t_r	Rise Time		--	6	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	7	--	
t_f	Fall Time		--	5	--	
Q_g	Total Gate Charge	$I_D=2A, V_{DD}=30V$ $V_{GS}=10V$	--	4	--	nC
Q_{gs}	Gate to Source Charge		--	1.0	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	1.0	--	

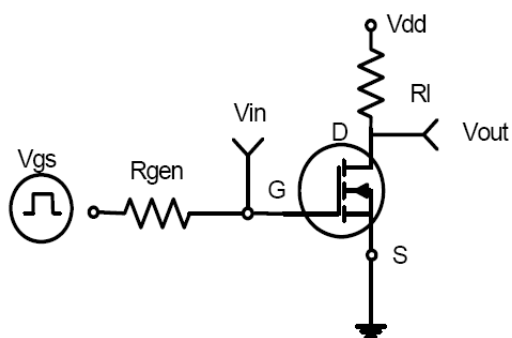
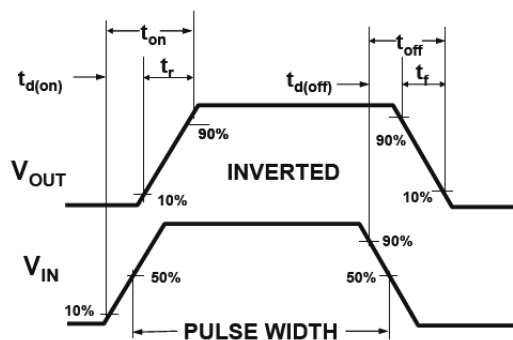
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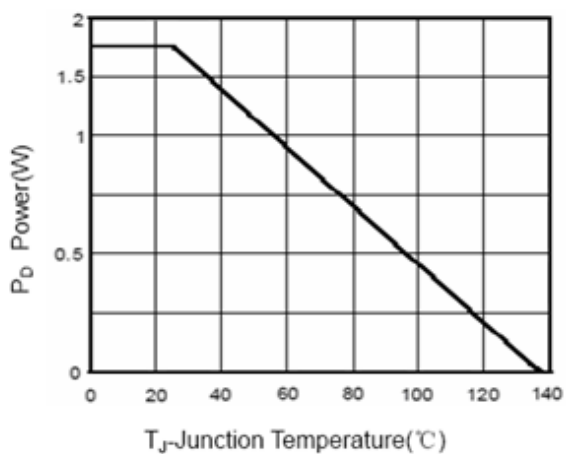
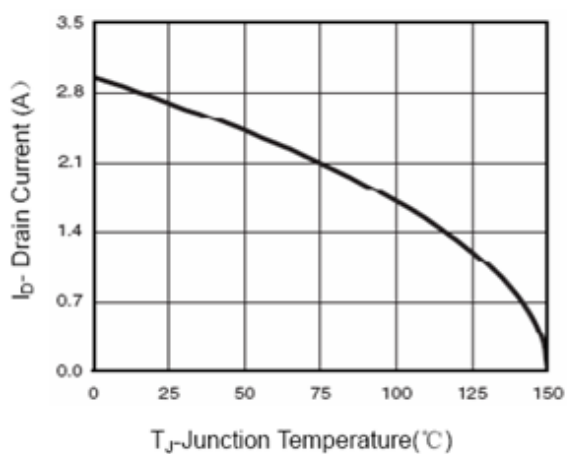
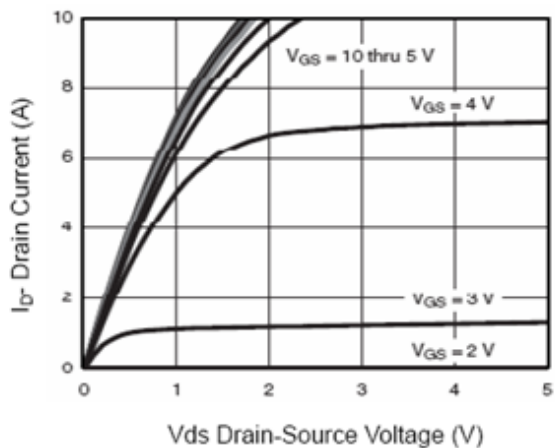
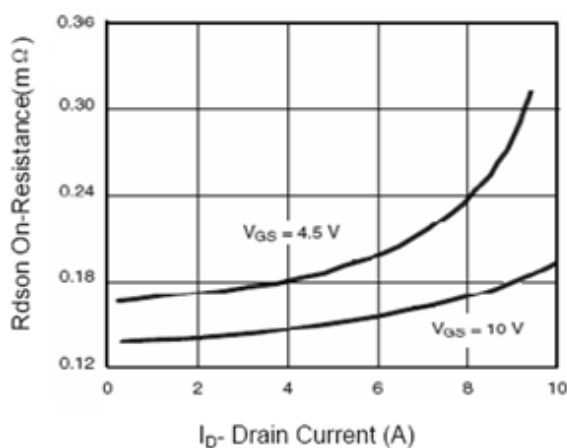
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	2.0	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	8	A
V_{SD}	Diode Forward Voltage	$I_S = 2.0A, V_{GS} = 0V$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$I_S = 2.0A, T_j = 25^\circ C$	--	70	--	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s, V_{GS} = 0V$	--	140	--	nC
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

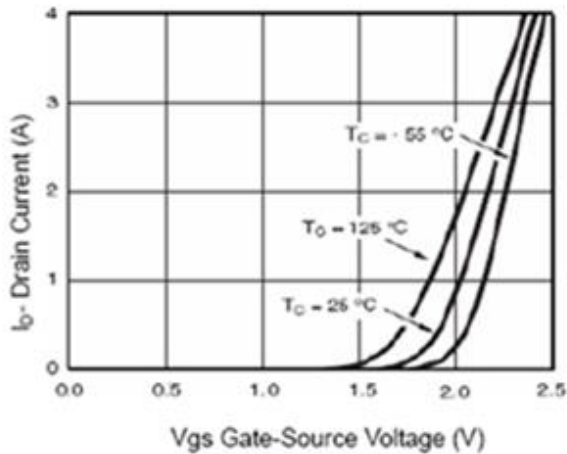
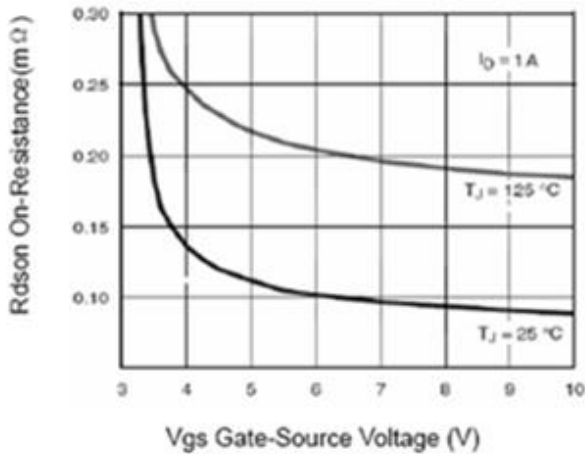
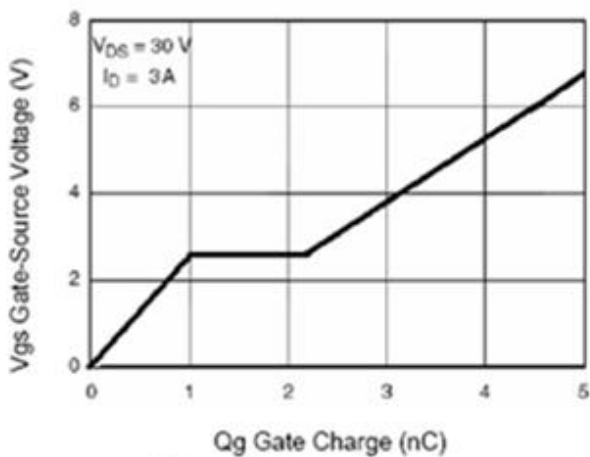
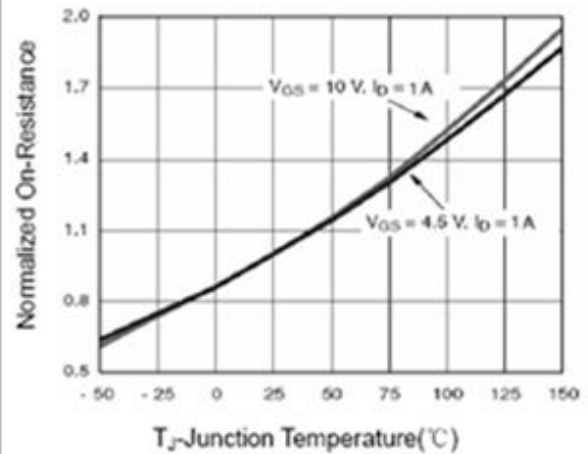
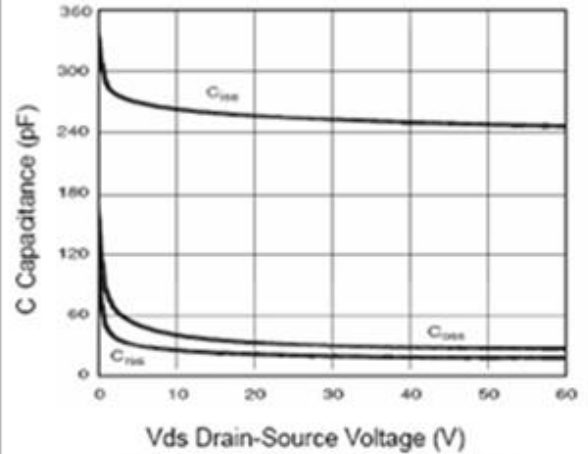
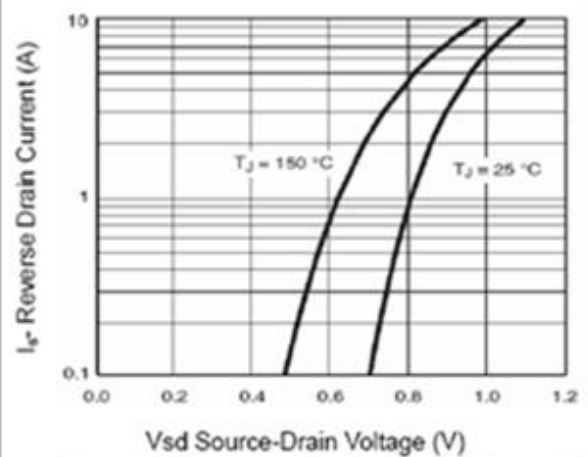
Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	74	$^\circ C/W$

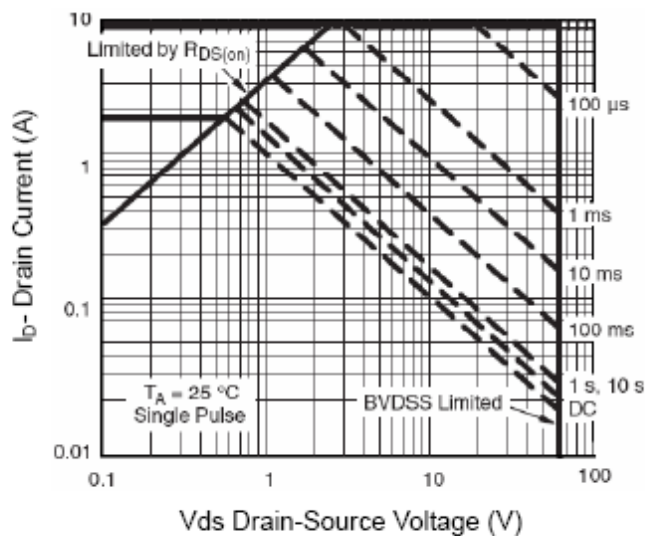
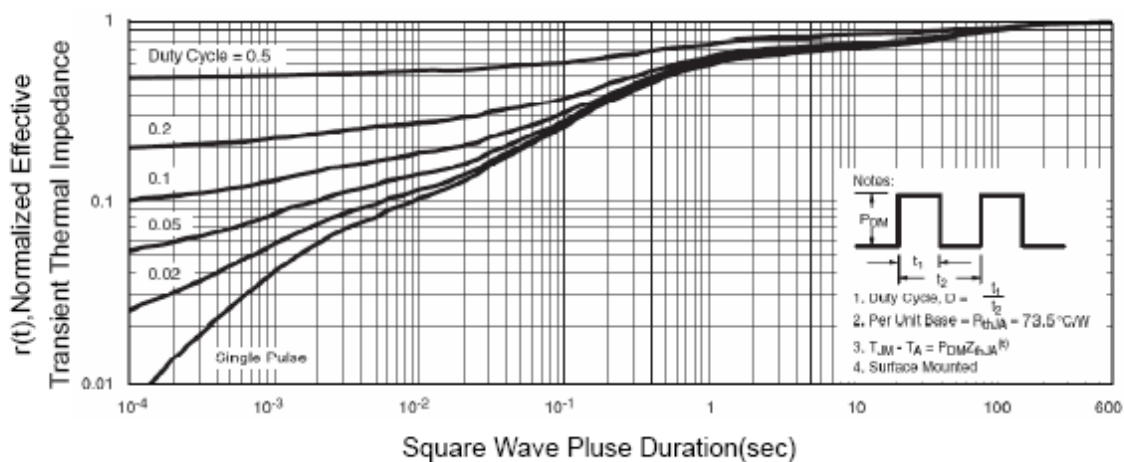
^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a3}: $I_{SD} = 3.0A, di/dt \leq 100A/\mu s, V_{DD} \leq BV_{DS}, \text{Start } T_j = 25^\circ C$

Typical Electrical and Thermal Characteristics

Figure 1: Switching Test Circuit

Figure 2: Switching Waveforms

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Figure 1: Switching Test Circuit

Figure 3 Power Dissipation
Figure 2: Switching Waveforms

Figure 4 Drain Current

Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance


Figure 7 Transfer Characteristics

Figure 9 Rdson vs Vgs

Figure 11 Gate Charge

Figure 8 Drain-Source On-Resistance

Figure 10 Capacitance vs Vds

Figure 12 Source-Drain Diode Forward

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Figure 13 Safe Operation Area

Figure 14 Normalized Maximum Transient Thermal Impedance

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